Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's	*Revisio*	*Datum:*	*Seite:*
PRINTED CIRCUIT BOARDS	**01**	**4.11.2001**	**1/1**

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
06	**151**	**FR4**	**35**	**L20.35_10.35**	**P10**	**s1**

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_151_FR4_35_L20.35_10.35_p10_s1

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	100µ	Prepreg	**(100 µ PrePreg-Type: 2125)**	B
	100µ	Prepreg		B
Layer-2	35µ	Copper		A1, B
	200µ	L-FR4		A1, B
Layer-3	35µ	Copper		A1, B
	100µ	Prepreg		B
	100µ	Prepreg		B
	100µ	Prepreg		B
	100µ	Prepreg		B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-4	35µ	Copper		A2, B
	100µ	L-FR4		A2, B
Layer-5	35µ	Copper		A2, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-99	35µ	Copper		B

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